AMENDMENTS TO THE SPECIFICATION

Please amend the title of the application as follows:

SEED CRYSTAL CONSISTING OF SILICON CARBIDE SINGLE CRYSTAL AND METHOD FOR PRODUCING INGOT USING THE SAME

Please replace the fourth paragraph on page 4 with the following amended paragraph:

Polytype of silicon carbide single crystal is almost determined by face polarity of a {0001} both type face crystal used for crystal growth. Regarding the {0001} face, there are two kinds of the (0001) Si face and the (000-1) C face which are different in polarity, and the outermost surfaces of respective faces are covered with a silicon atom layer and a carbon atom layer. A word {0001} is a generic term of these two faces.

Please replace the first paragraph on page 13 with the following amended paragraph:

Note that the angle inclined with respect to a (11-20) face of the single crystal growing face is called "off-angle" and a direction introducing the off-angle is called "off-direction" in the following explanation. As shown in FIG. 3, the off-direction is in the plane including the directions <0001> and [1-100], and the normal line of the single crystal growing face is in the plane including the off-direction and the <11-20> [11-20] direction.

Please replace the third paragraph on page 15 with the following amended paragraph:

When the angle ß is 45 degrees or more and 135 degrees or less, or when it is -135 degrees or more and -45 degrees or less, the off-direction comes to be nearer to the <1 100> [1-100] direction than the <0001> direction. Between this case and the case where the off-direction comes to be near to the <0001> direction, the structure of the steps and the like

differ from each other. And when the off-direction comes near to the <1-100> [1-100] direction, arbitrariness remains in an adsorption arrangement of silicon carbide molecules in the step so that a stacking fault can be generated. Therefore, the off-direction is required to be a direction inclined by -45 degrees or more and 45 degrees or less from a <0001> direction to the [1-100] direction.

Please replace the second paragraph on page 33 with the following amended paragraph:

Using the crystal growth system shown in FIG. 6, a silicon carbide single crystal was produced. Specifically, first, a wafer was cut from a 4H-type silicon carbide single crystal which had grown in the [000-1] C direction. At this time, the silicon carbide single crystal in which micropipe defects were contained but no stacking faults existed was used. Regarding the cut face, a face inclined at an angle of 10 degrees with respect to the (11-20) face of the silicon carbide single crystal in the [0001] Si direction was taken as the cut face ($\alpha = 10^{\circ}$, $\beta = 0^{\circ}$). Incidentally, the deviation of the off-direction from the $\frac{\{000-1\}Si}{[0001]Si}$ direction was set to be within \pm 1°.